Title (en)

UNDERFILLING MATERIAL FOR FLIP-CHIP FITTED PRINTED CIRCUIT BOARDS, A PRINTED CIRCUIT BOARD EQUIPPED THEREWITH, AND A METHOD FOR FILLING RATIO VERIFICATION OF CHIPS WHICH ARE UNDERFILLED THEREWITH

Title (de)

UNTERFÜLLMATERIAL FÜR FLIP-CHIP-BESTÜCKTE LEITERPLATTEN, DAMIT AUSGERÜSTETE LEITERPLATTE SOWIE VERFAHREN ZUR FÜLLGRADÜBERPRÜFUNG VON DAMIT UNTERFÜLLTEN CHIPS

Title (fr)

MATERIAU D'APPOINT EN CAS DE REMPLISSAGE INSUFFISANT POUR CARTES DE CIRCUITS MUNIES DE PUCES A BOSSES, CARTE DE CIRCUIT AINSI POURVUE ET PROCEDE DE SURVEILLANCE DU NIVEAU DE REMPLISSAGE DE PUCES MUNIES DUDIT MATERIAU D'APPOINT

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Application

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Abstract (en)

[origin: DE19808516A1] The invention relates to a method for verifying the distribution and the filling ratio of underfilling materials by means of X-ray inspection, for example, to detect how they are mounted between the chip and the substrate during or after the soldering of chips on a substrate. Said substrate is provided for mechanical support and for supporting the solder bumps. According to the invention, an auxiliary substance or filling substance which absorbs X-rays is incorporated in the underfilling material. The invention makes it possible to reliably test such underfilling stabilizations also during a running production process for fitted printed circuit boards.

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